



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-06-19
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGF7NB60SL	XSPF*LHE2662	A	3068	2018-06-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	Through-hole	
Comment	TO 220 ISO FULL PACK IN LINE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015			
Query			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			FALSE
Exemption Id.	Description		
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)		

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017			
Query			Response
1 - Product(s) meets EU ELV requirements without any exemptions			FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			TRUE
Exemption Id.	Description		
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)		

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.67	Leadframe	355
Lead	5.98	Soft solder	3148

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	XSPF*LHE2662					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	8.667	mg	supplier	die	Silicon (Si)	7440-21-3		8.571	mg	988924	4511
				supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	6807	31
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	1269	6
				supplier	Passivation	Silicon Oxide	7631-86-9		0.026	mg	3000	14
Leadframe	M-004 Copper and its alloys	605.985	mg	supplier	alloy	Copper (Cu)	7440-50-8		604.469	mg	997498	318142
				supplier	alloy	Iron (Fe)	7439-89-6		0.605	mg	998	318
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.182	mg	300	96
				supplier	metallization	Nickel (Ni)	7440-02-0		0.674	mg	1113	355
Soft solder	Solder	6.264	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	5.982	mg	954981	3148
				supplier	solder	Silver (Ag)	7440-22-4		0.157	mg	25064	83
				supplier	solder	Tin (Sn)	7440-31-5		0.125	mg	19955	66
				supplier	metallization	Phosphorus (P)	7723-14-0		0.055	mg	91	29
Bonding wires	M-011 Other inorganic materials	0.932	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.928	mg	995708	488
				supplier	wire	Magnesium (Mg)	7439-95-4		0.004	mg	4292	2
				supplier	mold compound	Quartz	14808-60-7		890.600	mg	700000	468737
				supplier	mold compound	Silica, vitreous	60676-86-0		95.422	mg	75000	50222
Encapsulation	M-011 Other inorganic materials	1272.286	mg	supplier	mold compound	Epoxy resin	25068-38-6		178.120	mg	140000	93747
				supplier	mold compound	phenol resin	29690-82-2		89.060	mg	70000	46874
				supplier	mold compound	metal hydroxide	21645-51-2		12.723	mg	10000	6696
				supplier	mold compound	carbon black	1333-86-4		6.361	mg	5000	3348
Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087